

AF/1725
PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE BOARD OF PATENT APPEALS AND INTERFERENCES

Re application of:

TAGUCHI ET AL

Application No.: 09/642,765 Art Unit: 1725
Filed: August 22, 2000 Examiner: C. Cooke
For: LEAD-FREE SOLDER PASTE
FOR REFLOW SOLDERING

TRANSMITTAL OF APPEAL BRIEF

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In support of the Notice of Appeal filed on January 17, 2003, the Appellants' Appeal Brief is submitted in triplicate with the appropriate fee. The Appellants petition to extend the date for submitting the Appeal Brief by one month, i.e., to and including April 17, 2003, and submit the appropriate fee therefor.

The Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR §1.17, including Appeal Brief filing fees pursuant to 37 CFR §1.17(f) and extension of time fees pursuant to 37 CFR §1.17(a)-(d), associated with this

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communication and to credit any excess payment to Deposit Account
No. 50-1079. A duplicate copy of this letter is attached.

Respectfully submitted,



Michael Tobias
Registration Number 32,948

#40
1717 K Street, N.W., Suite 613
Washington, D.C. 20036
Telephone: (301) 587-6541
Facsimile: (301) 587-6623
Date: April 17, 2003